CASE STUDY

FORMFACTOR™

Livermore, CA, USA

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SYNOVA
SYNOVA S.A.
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PRODUCT

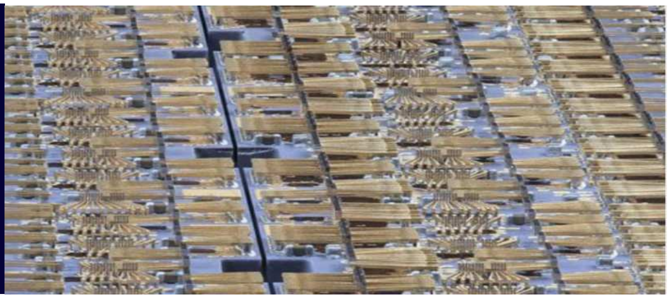
Thin Film Semi Substrates

- Lithographic thin-film Construction
- Alumina substrates

Semiconductor circuitized substrates used in wafer probe systems

LMJ used for:

- Singulation of ceramic circuits
- Hole-Drilling



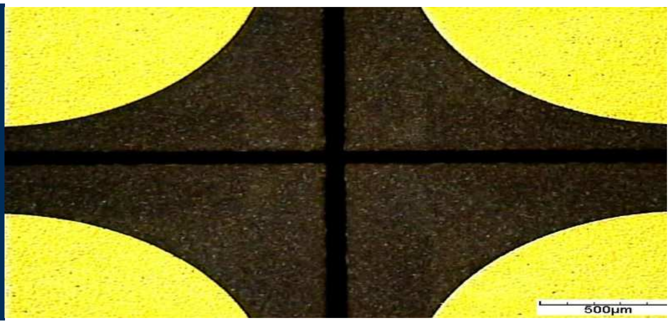
CHALLENGE

Dicing of high-density circuits on brittle material

Repeatable and High-Speed process to singulate substrates without damaging the adjacent circuitry

Main processing criteria:
- Tight Kerf
- Cleanliness of the cut
- Speed and repeatability

Machining technologies able to reach these criteria:
- Dicing Saw
- Laser MicroJet (LMJ) - water jet guided laser



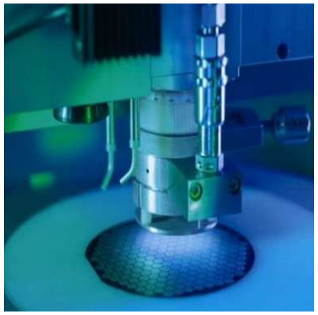
SOLUTION

Higher quality, enables new applications, better ROI

LMJ advantages versus Dicing Saw:
- Speed
- Repeatability

Installed machine type:
- Multiple LDS 300M
- 100 W green laser

LDS 300



Sources: www.ultrasource.com, Synova